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Zhang et al.

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(54) HEADSET

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Foreign Application Priority Data

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(51)

LOC (14) Cl.

..... 14-01

(52)

U.S. Cl.

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128/864–866; 381/380–381

CPC H04R 25/00; H04R 25/02; H04R 1/10;
H04R 1/1066; H04R 1/1016; H04R
1/1033; H04R 5/033; H04R 5/0335;
H04R 1/105; H04R 1/1058; H04R
1/1008; H04R 1/1075; H04R 1/1091

See application file for complete search history.

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(57) CLAIM

The ornamental design for a headset, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of the back, top, and left side view of a first embodiment showing the new design;

FIG. 2 is a perspective view of the back, bottom, and right side view thereof;

FIG. 3 is a top view thereof;

FIG. 4 is a bottom view thereof;

FIG. 5 is a right side elevation view thereof;

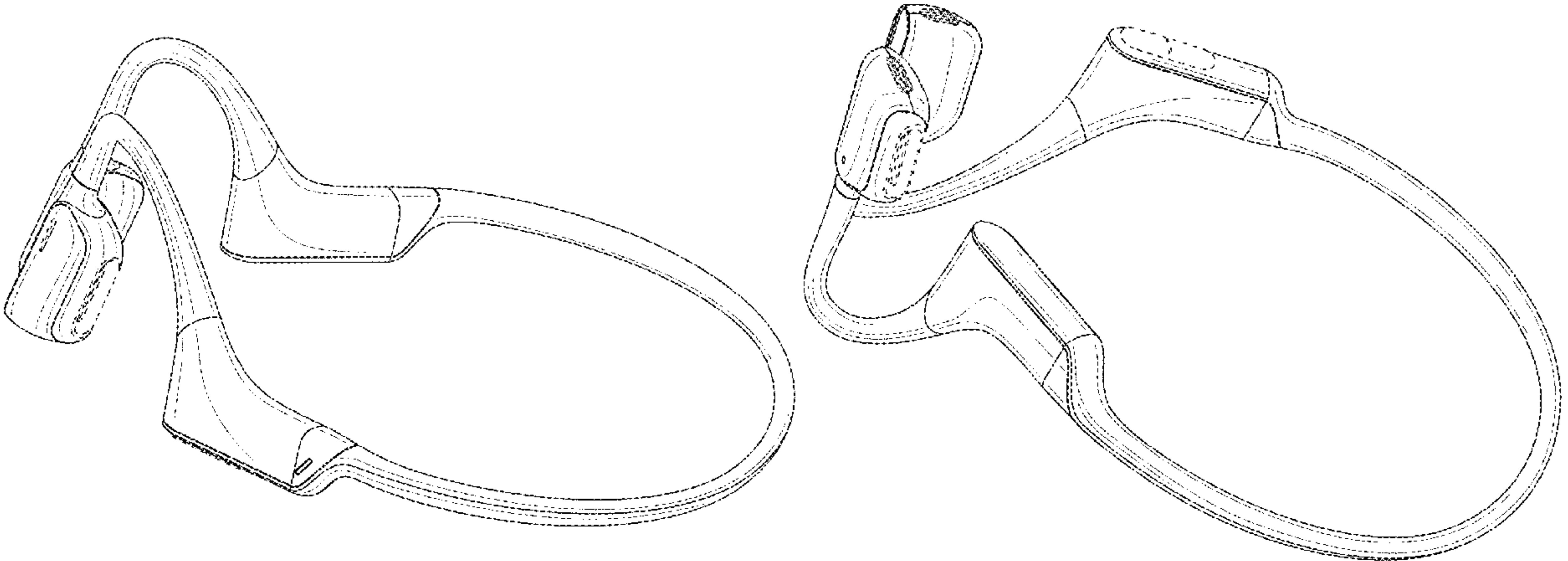
FIG. 6 is a left side elevation view thereof;

FIG. 7 is a rear elevation view thereof; and,

FIG. 8 is a front elevation view thereof.

The short dash broken lines indicate portions of the headset that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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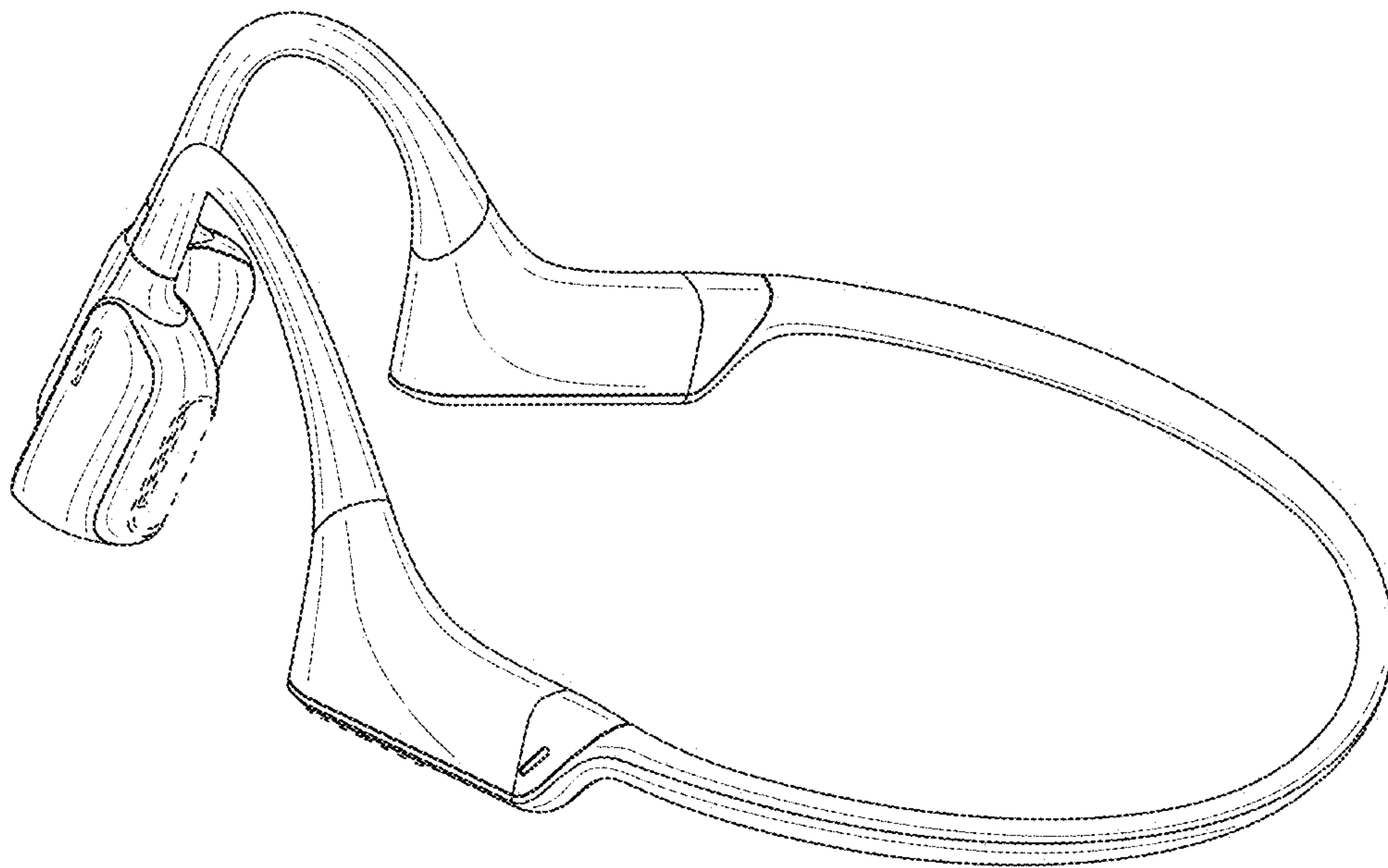


FIG. 1

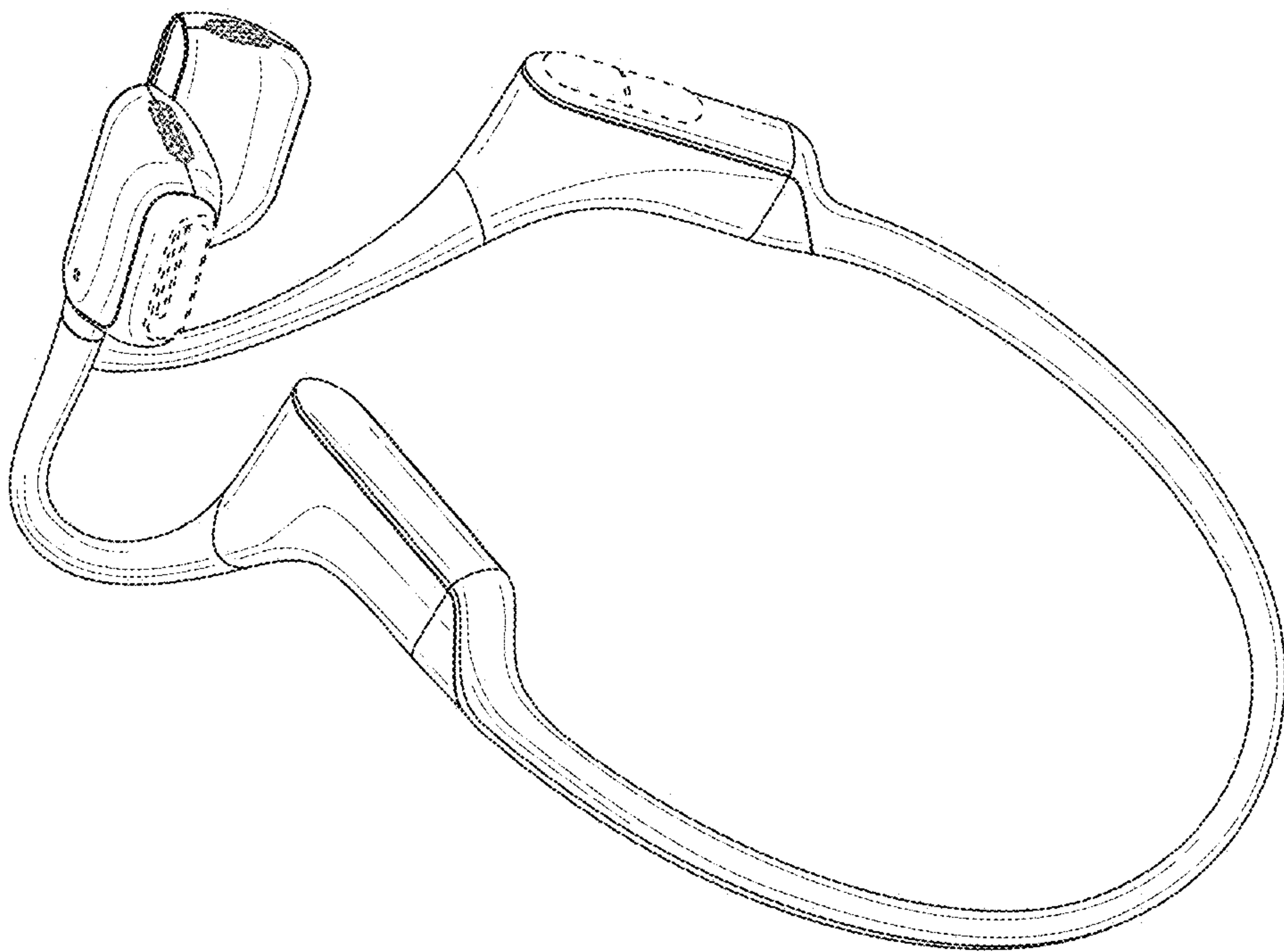


FIG. 2



FIG. 3



FIG. 4

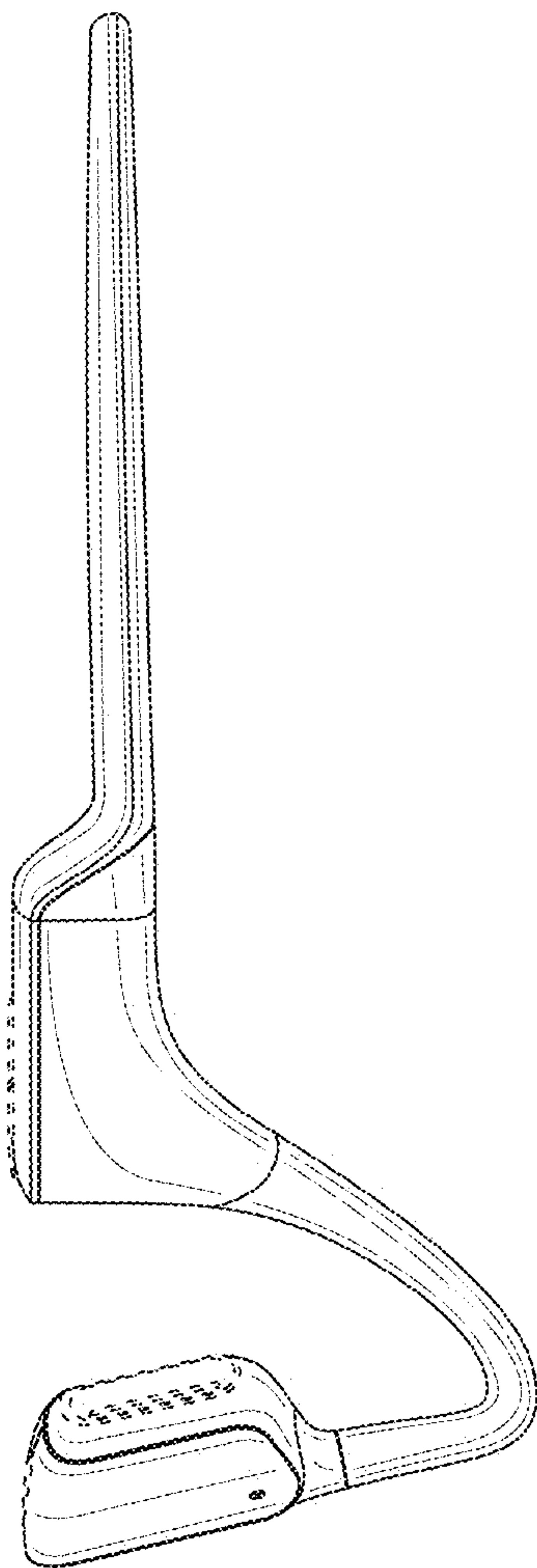


FIG. 5

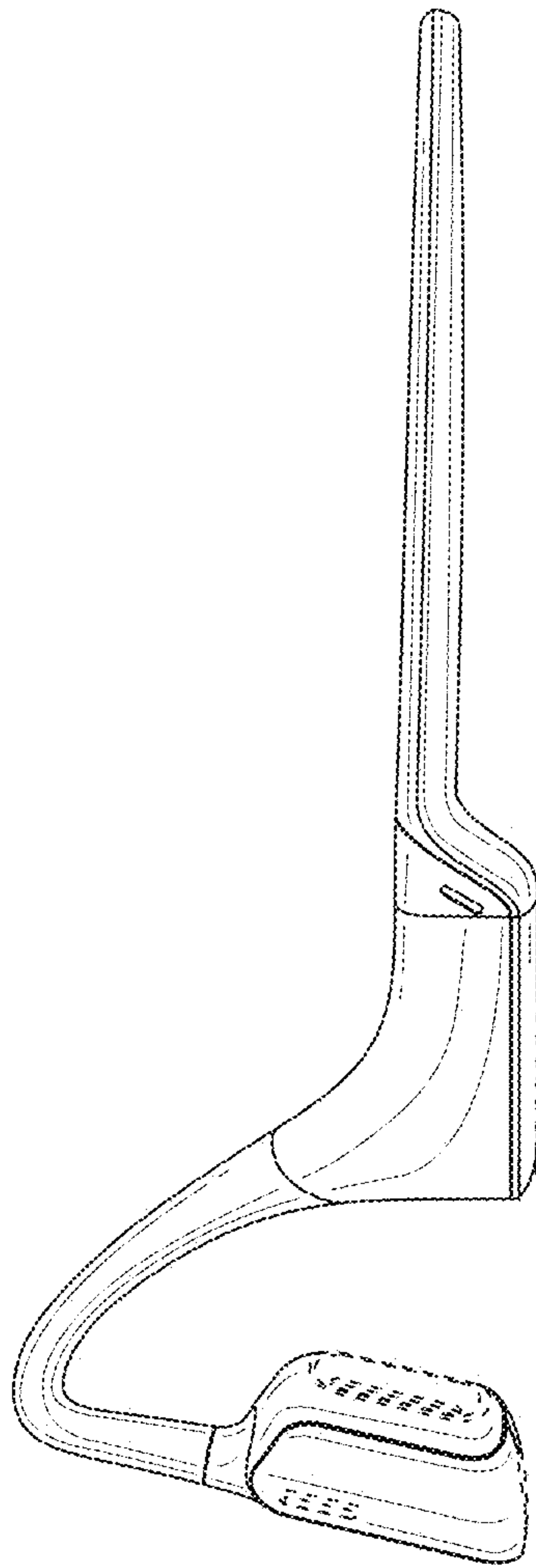


FIG. 6

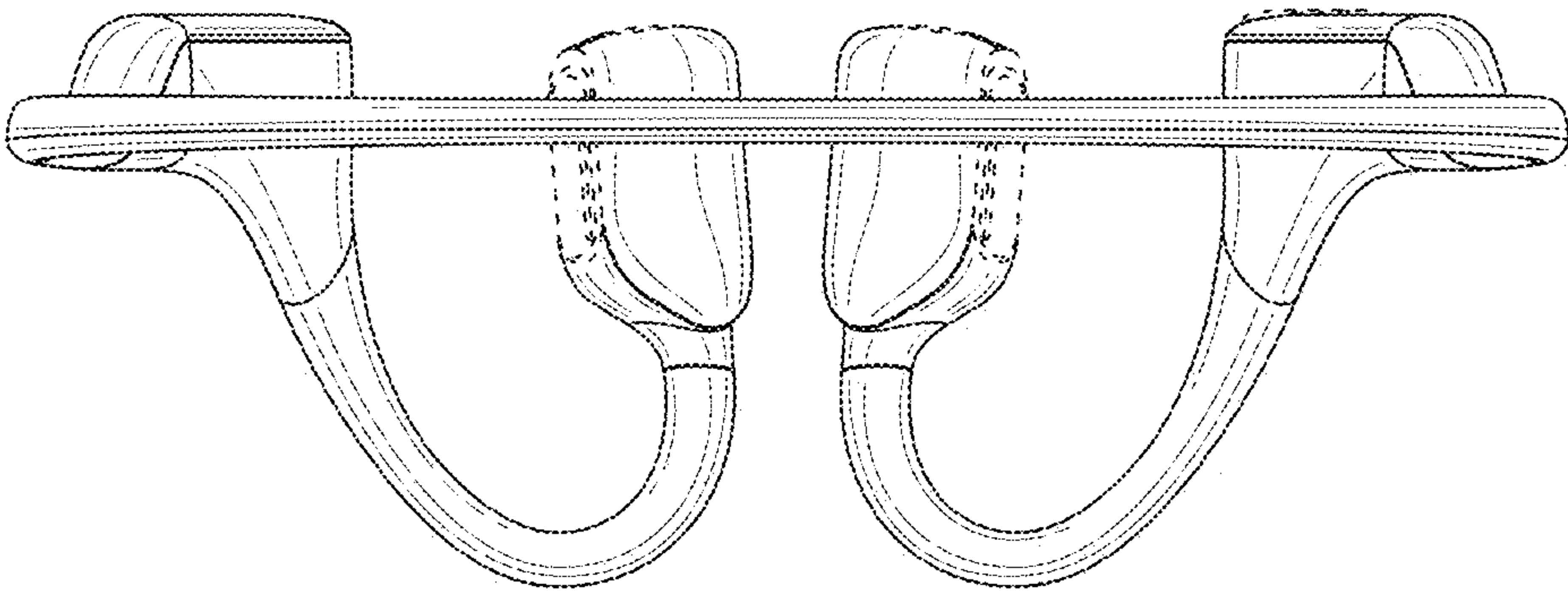


FIG. 7

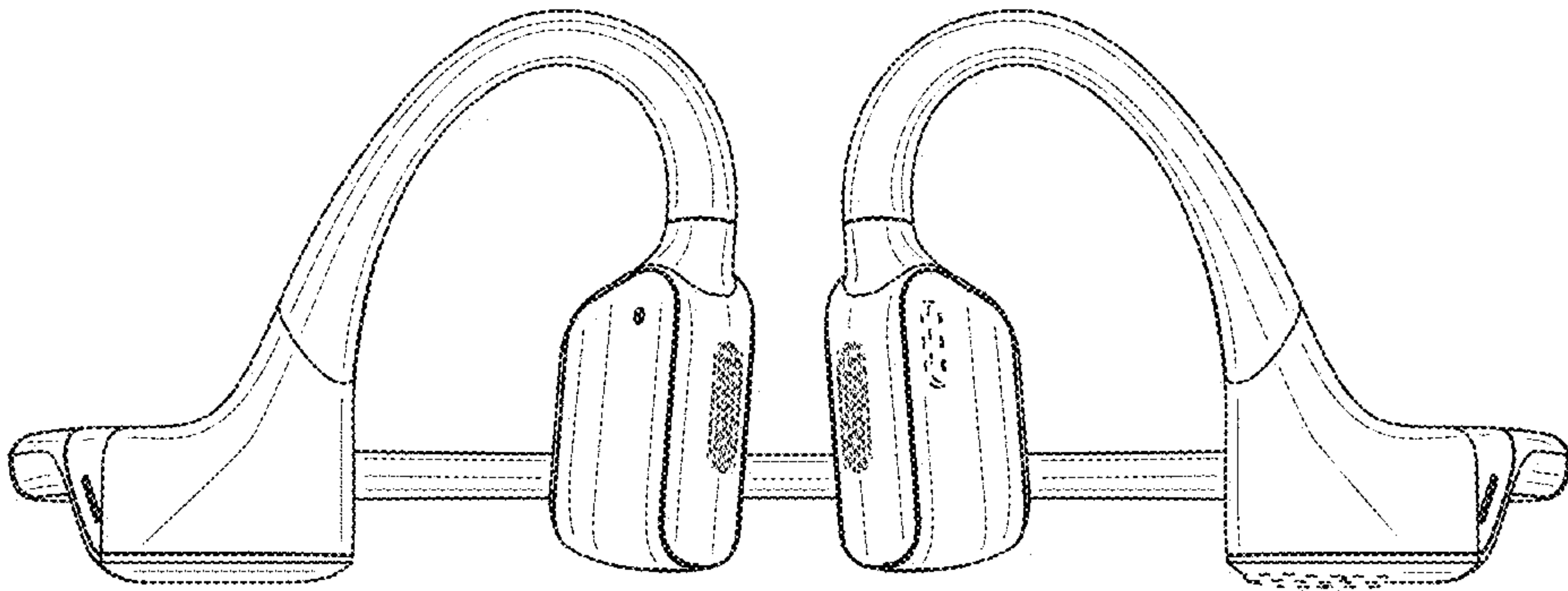


FIG. 8